Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	42378	(silicon with chip) or (silicon with die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/25 19:00
L2	265	(thermal with interface with material) and ((silicon with chip) or (silicon with die))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/25 19:33
L3	34	(thermal with interface with material) with (barrier with layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/25 19:37
L4	76	(thermal with interface with material) with (barrier$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/25 19:41
L5	90	(thermal with interface with material) with (adhesion$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/25 19:42